

2017 IEEE/SICE International Symposium on System Integration (SII2017)

## Special Session on “Distributed Haptic Sensor Integration”

organized by

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### Call for Papers

**Theme:** Haptic sensors can provide rich information about the contact state and can be used for various applications such as user interfaces or collaborative robots. Spatially distributed sensing points, for example integrated in an artificial skin, can potentially provide detailed tactile information. Embedded electronics and distributed computation are necessary to facilitate the integration; otherwise, an overwhelming amount of wires would require too much space. Advanced algorithms are needed to analyze and interpret the haptic data fast and accurate. This special session, therefore, aims to bring together experts in the fields of developing and integrating haptic sensors and tactile data analysis.

#### Topics of interest include, but are not limited to:

- Haptic sensor development and integration
- Multimodal distributed tactile sensors
- Modular skin sensors;
- Soft/flexible/stretchable sensors;
- Large-scale data processing of tactile information
- Use of tactile data for interaction control
- Integration of haptic data with other sensing modalities (e.g. vision, inertial sensing)

**Submissions Procedure:** All the instructions for paper submission are included in the conference website <http://www.sii2017.org>. A good quality paper may be considered for publication in IEEE Transactions on Industrial Informatics subjects to further rounds of review

#### Deadlines:

Reception of full paper:	June 30, 2017
Paper acceptance notification:	September 20, 2017
Camera ready paper reception:	October 20, 2017